

#### Features:

1. Chip material: GaP (Green)

2. Emitted color: Green

3. Lens Appearance: Water clear

4. Designed for ease in circuit board assembly.

5. Black case enhance contrast ratio.

6. Solid state light source.

7. Reliable and rugged.

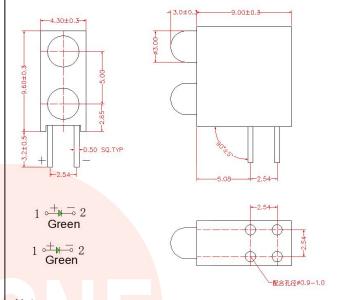
8. 3mm diameter package.

9. This product don't contained restriction substance, compliance ROHS standard.

### Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

#### Package dimensions



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

# ● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Green	Unit
Power Dissipation	Pd	75	mW
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current*1	I <sub>FP</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	Topr	-40℃~80℃	
Storage Temperature	Tstg	-40°C ~85°C	
Soldering Temperature	Tsol	260°C (for 5 seconds)	

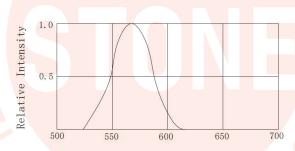
<sup>\*1</sup>Condition for I<sub>FP</sub> is pulse of 1/10 duty and 0.1msec width.



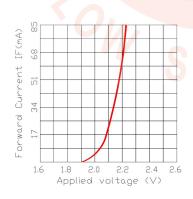
#### ■ Electrical and optical characteristics(Ta=25°C)

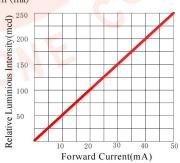
Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	Green	1.8		2.6	V
Luminous Intensity	lv	I <sub>F</sub> =20mA	Green	80		150	mcd
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	Green	-	-	10	μΑ
Peak Wave Length	λр	I <sub>F</sub> =20mA	Green	-	-	-	nm
Dominant Wave Length	λd	I <sub>F</sub> =20mA	Green	565	570	575	nm
Spectral Line Half-width	Δλ	I <sub>F</sub> =20mA	Green	-	30	-	nm
Viewing Angle	2θ <sub>1/2</sub>	Green	Green	-	30	-	deg

## Typical Electro-Optical Characteristics Curves

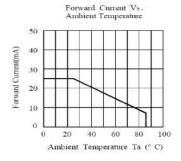


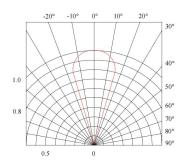
Wavelength (nm)





Forward Currend Vs Relative luminious Intensity



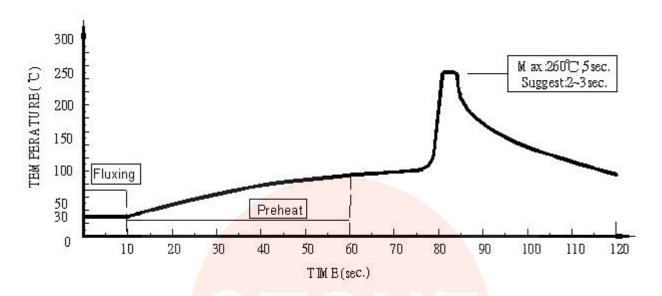


Angle distrbution

PCB



### Dip Soldering



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

## ●IRON Soldering

A: Max:  $350^{\circ}$ C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C Within 2 sec. One time only